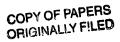


Honeywell Ref. No.:H0001609 Attny Dkt. No. 100665.022US1



#4/A 1.BELL: 6:13:02

Art Unit: 2827 Examiner: Cuneo, Kamand Serial No.: 09/752,538 Inventor: Ohr, Stephen

RECEIVELY
JUN-7 2002
TECHNOLOGY CENTER 28"

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE WASHINGTON, D.C. 20231

Inventor:

Ohr, Stephen

Serial No:

09/752,538

Filed:

December 28, 2000

For:

Layered Circuit Boards

And Methods Of Production Thereof

Examiner: Cuneo, Kamand

Art Unit: 2827

Client Ref. No.: H0001609 (4960) Attorney Docket No.: 100665.022US1

RESPONSE TO OFFICE ACTION

The Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

Dear Sir:

This paper responds to the Office Action dated February 27, 2002. Please enter the following:

IN THE CLAIMS

Cancel claims 10-18.

19. (Added) A sublamination layer, comprising:

- a single layer etched reference plane having a top surface and a bottom surface, the reference plain being formed by simultaneously etching both sides of a single layer of material;
- a first signal layer coupled to the top surface with a first bond-ply material;
- a second signal layer coupled to the bottom surface with a second bond-ply material; and at least one of a through via.

Honeywell Ref. No.:H0001609 Attny Dkt. No. 100665.022US1 Art Unit: 2827 Examiner: Cuneo, Kamand Serial No.: 09/752,538 Inventor: Ohr, Stephen

20. (Added) The sublamination layer of claim 19 wherein the reference plane is thicker than either the first signal layer or the second signal layer.

IN THE DRAWINGS

A single page of replacement figures accompanies this transmittal. Please supplement the figures 1-4 on the accompanying page for figures 1-4 as filed.

REMARKS

Added Claims

Claims 19 and 20 were added, but no new matter was introduced. Claim 19 recites the same elements as claim 1 as filed, and also recites "the reference plain being formed by simultaneously etching both sides of a single layer of material". Support for this recitation can be found on page 6, lines 5-11 of the specification as filed. Claim 20 adds the recitation that "the reference plane is thicker than either the first signal layer or the second signal layer". Support for this recitation is found on page 5, lines 27-30.

Drawing Objections

The drawings were objected to for various reasons. Such rejections are moot in light of the drawing amendments proposed herein.

35 USC § 102

Claims 1-4 and 7-9 were rejected under 35 USC § 102(b) as being anticipated by Wiley (US4854038). The applicant disagrees as Wiley does not teach a sublamination layer as claimed in claims 1-4 and 7-9.

In particular, claim 1 recites an "etched" reference plane. Copper sheet 2 of Wiley, which the Office asserts qualifies as the claimed reference plane, is formed by drilling, not etching (see column 3, lines 21-23). As such, copper sheet 2 is not an etched reference plane, and Wiley does not anticipate any of claims 1-4 or 7-9.

35 USC § 103

Claims 6-7 were rejected under 35 USC § 103 as being obvious over Wiley. The applicant disagrees. Among other things, claims 6-7 are all allowable as being dependent upon allowable claims.

Honeywell Ref. No.:H0001609 Attny Dkt. No. 100665.022US1 Art Unit: 2827 Examiner: Cuneo, Kamand Serial No.: 09/752,538 Inventor: Ohr, Stephen

ATTACHED MARKED-UP VERSION OF CHANGES

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE".

REQUEST FOR ALLOWANCE

Claims 1-9 and 19-20 are pending in this application. The applicant requests allowance of all pending claims.

Respectfully submitted,

Rutan & Tucker, LLP

By:

David J. Zoetewey Reg. No. 46264

Attorneys for Applicant(s) 611 Anton Boulevard, Fourteenth Floor Costa Mesa, CA 92626-1998

Tel: (714) 641-5100 Fax: (714) 546-9035

Dated: May 16, 2002